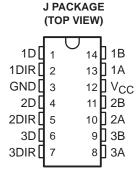
DW PACKAGE

(TOP VIEW)

- Three Bidirectional Transceivers
- Driver Meets or Exceeds ANSI Standard EIA/TIA-422-B and RS-485 and ITU Recommendation V.11
- Two Skew Limits Available
- Designed to Operate Up to 20 Million Data Transfers per Second (FAST-20 SCSI)
- High-Speed Advanced Low-Power Schottky Circuitry
- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- Wide Positive and Negative Input/Output Bus Voltage Ranges
- Driver Output Capacity . . . ±60 mA
- Thermal Shutdown Protection
- Driver Positive- and Negative-Current Limiting
- Receiver Input Impedances . . . 12 k Ω Min
- Receiver Input Sensitivity . . . ±300 mV Max
- Receiver Input Hysteresis . . . 60 mV Typ
- Operate From a Single 5-V Supply
- Glitch-Free Power-Up and Power-Down Protection
- Feature Independent Direction Controls for Each Channel

1D [20 1B 1DIR ∏ 19∏ 1A ис П 18 NC 3 GND [4 17 Пис NC [] 5 16 V_{CC} 2D ∏ 6 15 **□** 2B 2DIR ∏ 7 14 🛮 2A NC 🛮 8 13 3B 3D **[**] 9 12 🛮 3A 3DIR [] 10 11 ∏ NC

NC - No internal connection



description

The SN75ALS170 and SN75ALS170A triple differential bus transceivers are monolithic integrated circuits designed for bidirectional data communication on multipoint bus transmission lines. It is designed for balanced transmission lines and the driver meets ANSI Standards EIA/TIA-422-B and RS-485 and both the driver and receiver meet ITU Recommendation V.11. The SN75ALS170A is designed for FAST-20 SCSI and can transmit or receive data pulses as short as 30 ns with a maximum skew of 5 ns.

The SN75ALS170 and SN75ALS170A operate from a single 5-V power supply. The drivers and receivers have active-high and active-low enables, respectively, which are internally connected together to function as a direction control. The driver differential outputs and the receiver differential inputs are connected internally to form differential input/output (I/O) bus ports that are designed to offer minimum loading to the bus when the driver is disabled or $V_{CC} = 0$. These ports feature wide positive and negative common-mode voltage ranges making the device suitable for party-line applications.

The SN75ALS170 and the SN75ALS170A are characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

SKEW LIMIT	PART NUMBER					
10 ns	SN75ALS170DW	SN75ALS170J				
5 ns	SN75ALS170ADW					



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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Function Tables

EACH DRIVER

INPUT	NPUT DIR		PUTS
D	DIK	Α	В
Н	Н	Н	L
L	Н	L	Н
X	L	Z	Z

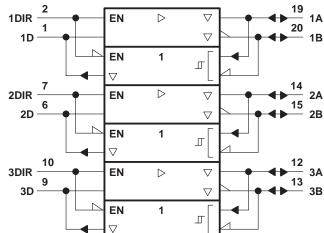
EACH RECEIVER

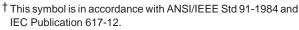
DIFFERENTIAL INPUTS A – B	DIR	OUTPUT R
V _{ID} ≥ 0.3 V	L	Н
$-0.3 \text{ V} < \text{V}_{\text{ID}} < 0.3 \text{ V}$	L	?
$V_{ID} \le -0.3 V$	L	L
X	Н	Z
Open	L	Н

H = high level, L = low level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

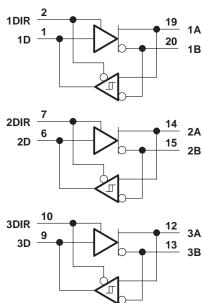
logic symbol†

ΕN \triangleright ∇ 20 ∇



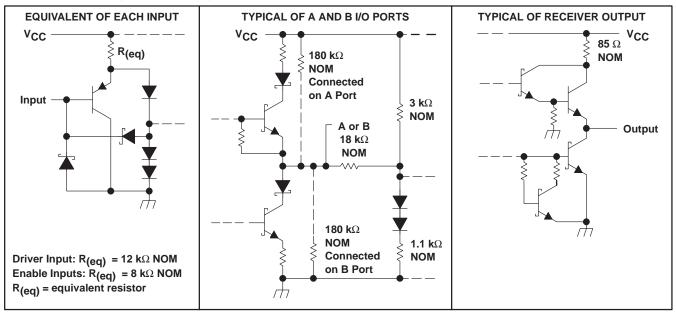


Pin numbers shown are for the DW package.



logic diagram (positive logic)

schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	7 V
Voltage range at any bus terminal	–7 V to 12 V
Enable input voltage, V _I	5.5 V
Continuous total power dissipation	. See Dissipation Rating Table
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{Stq}	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DW package	
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: J package	300°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.

DISSIPATION RATING TABLE

T _A ≤ 25°C POWER RATING		DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING		
DW	1125 mW	9.0 mW/°C	720 mW		
J	1025 mW	8.2 mW/°C	656 mW		



SN75ALS170, SN75ALS170A TRIPLE DIFFERENTIAL BUS TRANSCEIVER

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recommended operating conditions

			MIN	TYP	MAX	UNIT
Supply voltage, V _{CC}			4.75	5	5.25	V
Voltage at any bus terminal (separately or common	mada) Vi ar Vi a				12	V
Voltage at any bus terminal (separately or common	mode), vi or viC				-7	V
High-level input voltage, VIH	D, DIR		2			V
Low-level input voltage, V _{IL}	D, DIR				0.8	V
Differential input voltage, VID (see Note 2)					±12	V
High lovel output output	Driver				-60	mA
High-level output current, IOH	Receiver				-400	μΑ
Low level output ourrent Lev	Driver				60	mΛ
Low-level output current, IOL	Receiver				8	mA
Operating free-air temperature, T _A			0		70	°C

NOTE 2: Differential-input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONI	TEST CONDITIONS†			MAX	UNIT
VIK	Input clamp voltage	I _I = -19 mA				-1.5	V
VO	Output voltage	IO = 0		0		6	V
VOH	High-level output voltage	V _{CC} = 4.75 V, V _{IL} = 0.8 V,	V _{IH} = 2 V, I _{OH} = -55 mA	2.7			V
VOL	Low-level output voltage	V _{CC} = 4.75 V, V _{IL} = 0.8 V,	V _{IH} = 2 V, I _{OL} = 55 mA			1.7	V
I Vod1 I	Differential output voltage	IO = 0		1.5		6	V
V _{OD2} Differential output voltage		$R_L = 100 \Omega$,	See Figure 1	1/2 V _{OD1} or 2§			V
		$R_L = 54 \Omega$,	See Figure 1	1.5	2.5	5	V
V _{OD3}	Differential output voltage	$V_{\text{test}} = -7 \text{ V to } 12 \text{ V},$	See Figure 2	1.5		5	V
Δ V _{OD}	Change in magnitude of differential output voltage¶					±0.2	V
Voc	Common-mode output voltage	R_L = 540 Ω or 100 Ω ,	R_L = 540 Ω or 100 Ω , See Figure 1			3 –1	٧
Δ Voc	Change in magnitude of common-mode output voltage¶					±0.2	V
	Outrot ourself	Output disabled,	V _O = 12 V			1	Λ
10	Output current	See Note 3	V _O = -7 V			-0.8	mA
lН	High-level input current	V _I = 2.4 V	_			20	μΑ
IIL	Low-level input current	V _I = 0.4 V				-400	μА
		V _O = -6 V	V _O = -6 V			-250	
	Chart singuit autout aumant	V _O = 0	V _O = 0			-150	mA
los	Short-circuit output current	$V_O = V_{CC}$				250	mA
		V _O = 8 V			250		
loo	Supply current	No load	Outputs enabled		69	90	mA
ICC	Зирріу сипепі	INO IOAU	Outputs disabled		57	78	IIIA

[†] The power-off measurement in ANSI Standard EIA/TIA-422-B applies to disabled outputs only and is not applied to combined inputs and outputs. ‡ All typical values are at V_{CC} = 5 V and T_A = 25°C. § The minimum V_{OD2} with a 100- Ω load is either 1/2 V_{OD1} or 2 V, whichever is greater.

NOTE 3: This applies for both power on and off; refer to EIA Standard RS-485 for exact conditions. The EIA/TIA-422-B limit does not apply for a combined driver and receiver terminal.



[¶] Δ | V_{OD} | and Δ | V_{OC} | are the changes in magnitude of V_{OD} and V_{OC} respectively, that occur when the input is changed from a high level to a low level.

SN75ALS170, SN75ALS170A TRIPLE DIFFERENTIAL BUS TRANSCEIVER

SLLS055D - AUGUST 1987 - REVISED SEPTEMBER 1995

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER			TEST COND	ITIONS	MIN	TYP [†]	MAX	UNIT
		ALS170	$R_L = 54 \Omega$,	C _L = 50 pF,	3	8	13	
		ALS170A	T _A =25°C,	See Figure 3	5.5	8	10.5	
^t d(OD)	Differential output delay time	ALS170	$R_{L1} = R_{L3} = 165 \Omega,$ $C_{I} = 60 pF,$	$R_{L2} = 75 \Omega,$ $T_A = 25^{\circ}C,$	3	8	13	ns
		ALS170A	See Figure 4	тд =25 О,	5.5	8	10.5	
			R_L = 54 Ω, See Figure 3	$C_L = 50 \text{ pF},$		1	5	ns
tsk(p)	Pulse skew [‡]		$R_{L1} = R_{L3} = 165 \Omega,$ $C_{L} = 60 pF,$	R_{L2} = 75 Ω, See Figure 4		1	5	ns
		ALS170	$R_L = 54 \Omega$,	C _L = 50 pF,			10	
	Skew limit§	ALS170A	See Figure 3				5	ns
tsk(lim)	Skew IIIIIts	ALS170	$R_{L1} = R_{L3} = 165 \Omega$,	$R_{L2} = 75 \Omega$,			10	115
		ALS170A	$C_L = 60 \text{ pF},$	See Figure 4			5	
t.(05)	Differential-output transition time		$R_L = 54 \Omega$, See Figure 3	$C_L = 50 \text{ pF},$	3	8	13	ne
^t t(OD)			$R_{L1} = R_{L3} = 165 \Omega$, $C_{L} = 60 pF$,	R_{L2} = 75 Ω, See Figure 4	3	8	13	ns

SYMBOL EQUIVALENTS

DATA SHEET PARAMETER	EIA/TIA-422-B	RS-485
Vo	V_{oa}, V_{ob}	V_{oa}, V_{ob}
∣VOD1 ∣	Vo	Vo
VOD2	$V_t (R_L = 100 \Omega)$	$V_t (R_L = 54 \Omega)$
∣V _{OD3} ∣		V _t (Test Termination Measurement 2)
V _{test}		V_{tst}
Δ V _{OD}	$ \vee_t - \overline{\vee}_t $	$ \vee_t - \overline{\vee}_t $
Voc	V _{os}	V _{os}
Δ Voc	$ V_{OS} - \overline{V}_{OS} $	$ V_{OS} - \overline{V}_{OS} $
los	I _{sa} , I _{sb}	
IO	I _{xa} , I _{xb}	I _{ia} , I _{ib}

[†] All typical values are at V_{CC} = 5 V and T_A = 25°C.
‡ Pulse skew is defined as the |t_d(ODH)-t_d(ODL)| of each channel.
§ Skew limit is the maximum difference in propagation delay times between any two channels of one device and between any two devices. This parameter is applicable at one V_{CC} and operating temperature within the recommended operating conditions.

RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST C	TEST CONDITIONS			MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	$V_0 = 2.7 V$,	$I_{O} = -0.4 \text{ mA}$			0.3	V
VIT-	Negative-going input threshold voltage	V _O = 0.5 V,	I _O = 8 mA	-0.3‡			V
V _{hys}	Hysteresis voltage (V _{IT+} - V _{IT-})				60		mV
VIK	Enable-input clamp voltage	I _I = -18 mA				-1.5	V
Vон	High-level output voltage	V _{ID} = 300 mV, See Figure 5	$I_{OH} = -400 \mu A,$	2.7			V
VOL	Low-level output voltage	$V_{ID} = -300 \text{ mV},$ See Figure 5	I _{OL} = 8 mA,			0.45	V
lo-	High-impedance-state output current	V _O = 2.4 V				20	μΑ
loz	nigh-impedance-state output current	V _O = 0.4 V				-400	μΑ
1.	Line input current	Other input = 0,	V _I = 12 V			1	mA
li	Line input current	See Note 4	V _I = -7 V			-0.8	IIIA
۱н	High-level enable-input current	V _{IH} = 2.7 V				20	μΑ
IJL	Low-level enable-input current	V _{IL} = 0.4 V				-100	μΑ
rį	Input resistance			12			kΩ
los	Short-circuit output current	$V_{ID} = 300 \text{ mV},$	V _O = 0	-15		-85	mA
loo	O combination of	No load	Outputs enabled		69	90	mA
ICC	Supply current	INO IOAU	Outputs disabled		57	78	IIIA

[†] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

NOTE 4: This applies for both power on and off; refer to EIA Standard RS-485 for exact conditions.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature range

	PARAMETER	_	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT	
t=	Propagation delay time, low-to-high-level	ALS170		9		19	ns	
^t PLH	output	ALS170A	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$ $C_L = 15 \text{ pF}, \qquad T_A = 25^{\circ}\text{C},$	11.5		16.5	115	
	Propagation delay time, high-to-low-level	ALS170	See Figure 6	9		19		
^t PHL	output	ALS170A		11.5		16.5	ns	
	Dulas atraus	ALS170			2	6		
^t sk(p)	Pulse skew§	ALS170A	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$			5	ns	
t \	Skew limit¶	ALS170	C _L = 15 pF, See Figure 6			10	no	
tsk(lim)		ALS170A	1			5	ns	

 $^{^{\}dagger}$ All typical values are at V_{CC} = 5 V and T_A = 25°C.



[‡] The algebraic convention, in which the less-positive (more-negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

[§] Pulse skew is defined as the |tpLH-tpHL| of each channel.

[¶] Skew limit is the maximum difference in propagation delay times between any two channels of one device and between any two devices. This parameter is applicable at one V_{CC} and operating temperature within the recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION

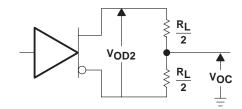


Figure 1. Driver V_{OD} and V_{OC}

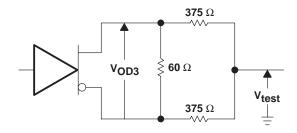
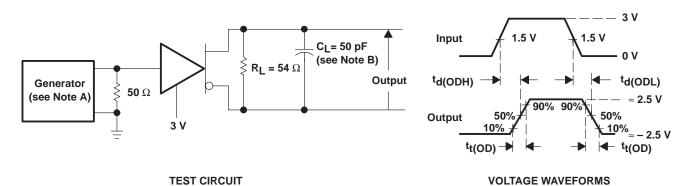


Figure 2. Driver V_{OD3}

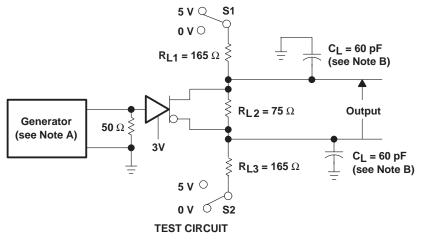


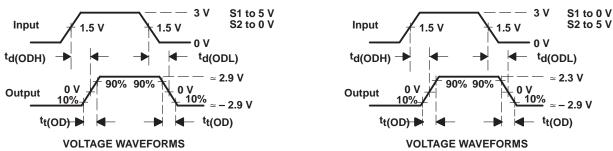
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq$ 6 ns, $t_f \leq$ 8 ns, $t_f \leq$ 8 ns, $t_f \leq$ 9 ns, t_f

B. C_L includes probe and jig capacitance.

Figure 3. Driver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION





- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$
 - B. C_I includes probe and jig capacitance.

Figure 4. Driver Test Circuit and Voltage Waveforms With Double-Differential-SCSI Termination for the Load

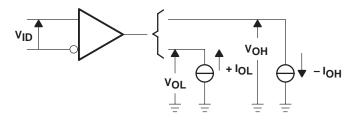
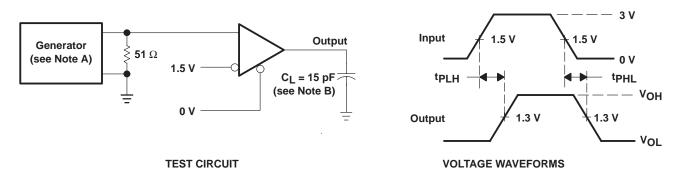


Figure 5. Receiver VOH and VOL

PARAMETER MEASUREMENT INFORMATION

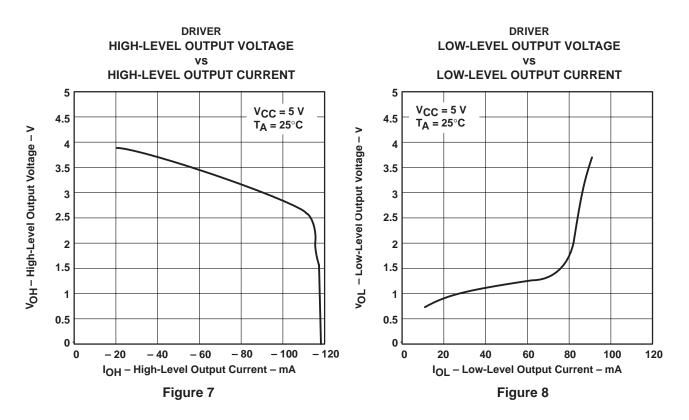


NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$

B. CL includes probe and jig capacitance.

Figure 6. Receiver Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

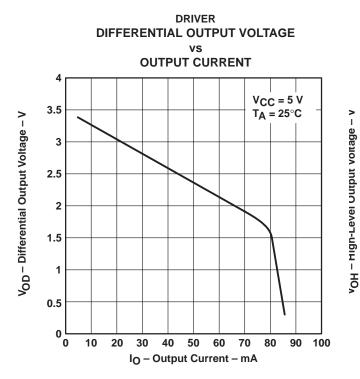
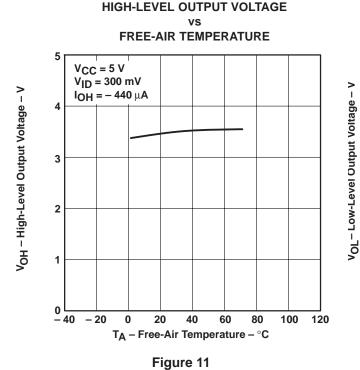


Figure 9

RECEIVER



RECEIVER
HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

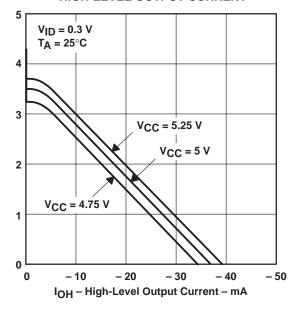


Figure 10

RECEIVER LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

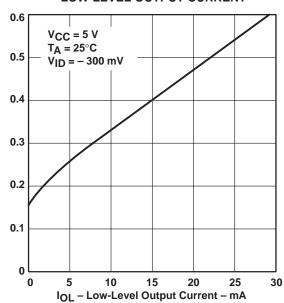
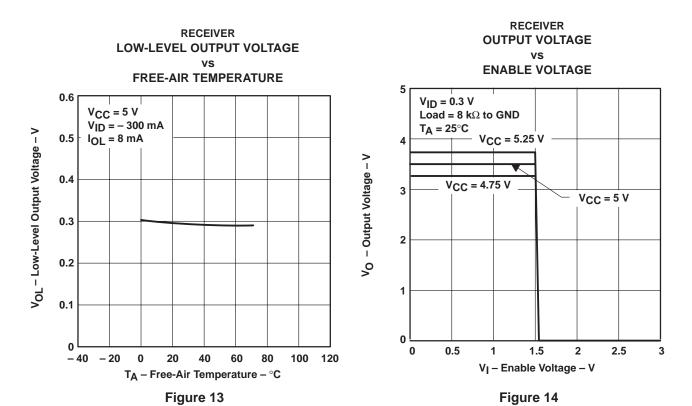


Figure 12

TYPICAL CHARACTERISTICS



RECEIVER **OUTPUT VOLTAGE ENABLE VOLTAGE**

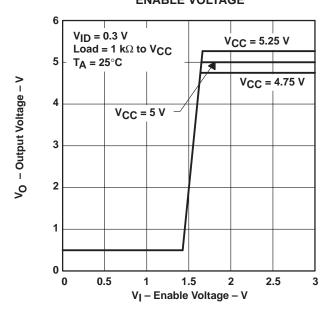
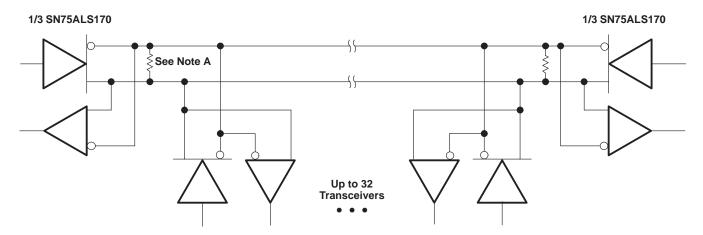


Figure 15

APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance. Stub lengths off the main line should be kept as short as possible.

Figure 16. Typical Application Circuit

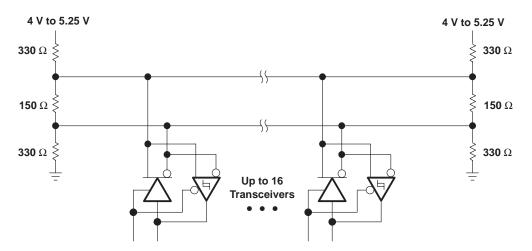


Figure 17. Typical Differential SCSI Application Circuit

APPLICATION INFORMATION

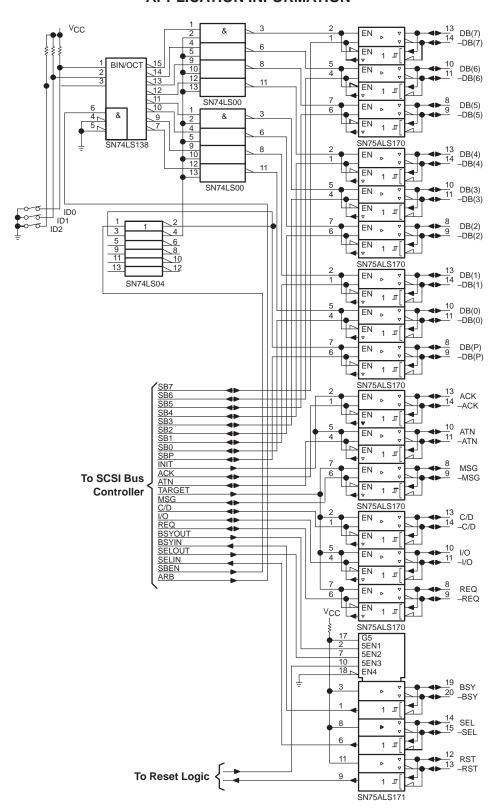


Figure 18. Typical Differential SCSI Bus Interface Implementation







com 10-May-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75ALS170ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS170J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

10-May-2007

information may not be available for release.
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jan-2013

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS170ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN75ALS170DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
SN75ALS170ADWR	SOIC	DW	20	2000	367.0	367.0	45.0	
SN75ALS170DWR	SOIC	DW	20	2000	367.0	367.0	45.0	

14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC—7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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